



E-QUAL ALLOY 30 SMQ SOLDER DATA

Typical E-Qual Alloy 30 SMQ Solder

EN.29453:1994 Alloy 30 Specification

61.8%	Sn	61.5 - 62.5%
1.95%	Ag	1.8 - 2.2%
0.0005%	Cu	0.05% max
<0.0002%	Zn	0.001% max
0.001%	Fe	0.02% max
0.002%	As	0.03% max
0.001%	Ni	*
0.02%	Bi	0.10% max
<0.0002%	Cd	0.002% max
<0.001%	Au	*
<0.001%	Al	0.001% max
Bal	Pb	Bal
0.005	Sum of all others	0.2 max

*No limit specified

Melting range 177-189°C

Comments: Low melting point alloy typically used in electronics to prevent silver and/or palladium leaching from component terminations.